

## **REMARKS**

This Amendment is in response to the Office Action mailed on July 9, 2004. Claims 1, 4, and 5 have been amended. Claims 2 and 3 have been canceled, and claim 9 has been added. Claim 1 has been amended to incorporate the limitations of claims 2 and 3 and to recite that the semiconductor chip is mounted on the conductor lead. Claims 4 and 5 have been amended to depend from claim 1. Claims 2 and 3 were canceled as being redundant in view of the amendments to claim 1. The above-referenced amendments to claim 1 and new claim 9 are supported at Figures 1a and 1b, Figure 2, Figure 5, and Figures 6a and 6b. Accordingly, no new subject matter has been added. Applicants submit that in view of the above amendments and the following remarks, the pending claims are in condition for allowance.

Claim 1 was rejected under 35 U.S.C. § 102(b) as being anticipated by Ichikawa et al. (U.S. 5,905,301). In view of the amendments to claim 1 incorporating the subject matter of claims 2 and 3, this rejection has been rendered moot. Applicants are not conceding the correctness of this rejection.

Claims 2 and 3 were rejected under 35 U.S.C. § 103(a) as being obvious over Ichikawa as applied to claim 1 and in further view of Gibson et al. (U.S. 6,621,140). This rejection is traversed. Applicants have treated this rejection as though it is directed at amended claim 1, which recites a semiconductor device comprising, among other things, a semiconductor chip sealed in a mold resin that is mounted on and connected to a portion of an inductance element having a meander planar shape that overlaps with a lower surface of the semiconductor chip. In accordance with the above-recited features, bonding wire is not used to connect the semiconductor chip with the inductance elements. Both Ichikawa et al. and Gibson et al. fail to disclose or suggest a semiconductor device according to claim 1.

The Office Action asserts that though Ichikawa et al. fails to describe an inductance element having a meandering planar shape Gibson et al. discloses an inductance segment having a plurality of alternative shapes, therefore, claim 1 is obvious. This assertion is flawed at least because the inductive segments disclosed in Gibson are necessarily connected to a semiconductor chip with bonding wires 20 and will result in variations and high-frequency characteristics that are avoided by the arrangement of claim 1. See Gibson et al. at Figure 3 and

column 3, line 30 through column 5, line 30. Since neither Ichikawa et al. nor Gibson et al. disclose a semiconductor device wherein the semiconductor chip is mounted on and connected to the inductance elements of a conductor lead, claim 1 is not obvious. Claims 4 through 8 depend on and further limit claim 1; therefore, they are not obvious for at least the same reasons.

New claim 9 is directed at a semiconductor comprising, among other things, a semiconductor chip, a mold resin sealing the semiconductor chip, and a plurality of conductor leads wherein the internal terminal portions of two of the conductor leads having the same shape has an inductance element portion with a width narrower than the external terminal portion and are arranged symmetrically with respect to the semiconductor chip, with the semiconductor chip being interposed therebetween. According to the above-recited features of claim 9, it is possible to reduce the mutual inductive influence between the internal terminal portions thereby allowing high-frequency characteristics to be stable. The above-recited features are not disclosed or suggested in Ichikawa et al. or Gibson et al.

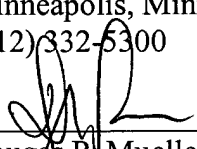
In particular, Ichikawa et al. and Gibson et al. fail to disclose or suggest internal terminal portions having the same shape arranged symmetrically with respect to the semiconductor chip with the semiconductor chip being interposed therebetween. Particularly, in Gibson et al. the inductance elements 22, are disposed adjacent each other. Therefore, the mutual inductive influence between the internal terminal portions are not balanced. Such an arrangement would result in unstable high-frequency characteristics that are avoided according to the arrangement of claim 9. Therefore, claim 9 is neither anticipated nor obvious over the cited references.

In view of the above amendments and remarks, Applicant respectfully requests a Notice of Allowance. If the Examiner believes a telephone conference would advance the prosecution of this application, the Examiner is invited to telephone the undersigned at the below-listed telephone number.

Respectfully submitted,

MERCHANT & GOULD P.C.  
P.O. Box 2903  
Minneapolis, Minnesota 55402-0903  
(612) 332-5300

Date: November 9, 2004



---

Douglas P. Mueller  
Reg. No. 00734  
DPM/JEL:sll

**23552**

PATENT TRADEMARK OFFICE